

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization International Bureau



(43) International Publication Date  
3 March 2005 (03.03.2005)

PCT

(10) International Publication Number  
WO 2005/019128 A2

(51) International Patent Classification<sup>7</sup>: C03C 25/00 (74) Agent: VERWELJ, P., D.; DSM Intellectual Property, P.O. Box 9, NL-6160 MA Geleen (NL).

(21) International Application Number:  
PCT/NL2004/000589

(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(22) International Filing Date: 20 August 2004 (20.08.2004)

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:  
JP2003-296196 20 August 2003 (20.08.2003) JP  
JP2003-326601 18 September 2003 (18.09.2003) JP

Published:

— without international search report and to be republished upon receipt of that report

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

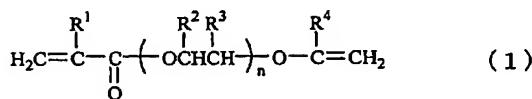
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(54) Title: RADIATION-CURABLE LIQUID RESIN COMPOSITION



(57) Abstract: The invention relates to a radiation -curable liquid resin composition comprising: (A) 20-90 wt% of a urethane (meth)acrylate oligomer, and (B) 1-35 wt% of - a monomer shown by the following formula (1), wherein R<sup>1</sup> represents a hydrogen atom or a methyl group, R<sup>2</sup> and R<sup>3</sup> individually represent a hydrogen atom or an alkyl group having 1-4 carbon atoms, R<sup>4</sup> represents a hydrogen atom or a methyl group, and n represents an integer of 1-6, or - a monomer including a hydroxyl group.